

## LOW-NOISE, VERY LOW DRIFT, PRECISION VOLTAGE REFERENCE

Check for Samples: [REF5020-Q1](#), [REF5025-Q1](#), [REF5030-Q1](#), [REF5040-Q1](#), [REF5045-Q1](#), [REF5050-Q1](#)

### FEATURES

- **Qualified for Automotive Applications**
- **Low Temperature Drift**
  - **Standard Grade: 8 ppm/°C (max)**
- **High Accuracy**
  - **Standard Grade: 0.1% (max)**
- **Low Noise: 3  $\mu\text{V}_{\text{PP}}$ /V**
- **EXCELLENT LONG-TERM STABILITY:**
  - **5 ppm/1000 hr (typ) after 1000 hours**
- **High Output Current:  $\pm 10$  mA**
- **Temperature Range:  $-40^{\circ}\text{C}$  to  $125^{\circ}\text{C}$**

### APPLICATIONS

- **16-Bit Data Acquisition Systems**
- **ATE Equipment**
- **Industrial Process Control**
- **Medical Instrumentation**
- **Optical Control Systems**
- **Precision Instrumentation**

### DESCRIPTION

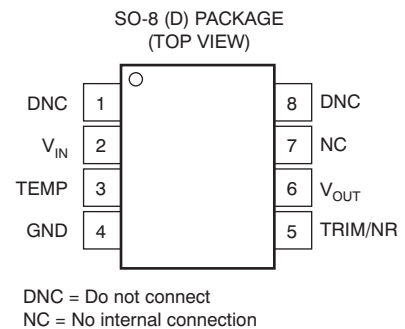
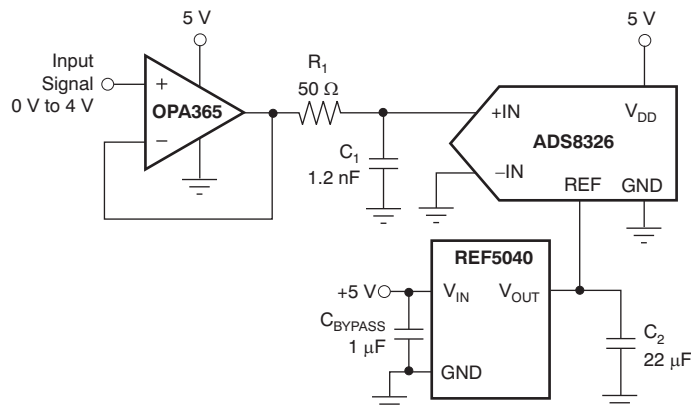
The REF50xx is a family of low-noise, low-drift, very-high precision-voltage references. These references are capable of both sinking and sourcing, and are very robust with regard to line and load changes.

Excellent temperature drift (3 ppm/°C) and high accuracy (0.05%) are achieved using proprietary design techniques. These features combined with very low noise make the REF50xx family ideal for use in high-precision data acquisition systems.

Each reference voltage is available in a standard-grade versions. The devices are offered in SO-8 packages and are specified from  $-40^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ .

**REF50xx Family**

MODEL	OUTPUT VOLTAGE
REF5020	2.048 V
REF5025	2.5 V
REF5030	3 V
REF5040	4.096 V
REF5045	4.5 V
REF5050	5 V



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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

## ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

PARAMETER	REF50xx		UNIT
	MIN	MAX	
Input voltage		18	V
Output short-circuit		30	mA
Operating temperature range	–40	125	°C
Storage temperature range	–65	150	°C
Junction temperature (T <sub>J</sub> max)		150	°C

- (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

## ESD RATINGS

Over operating free-air temperature range (unless otherwise noted).

PARAMETER		VALUE	UNIT
ESD	REF5020AQDRQ1	500	V
	REF5030AQDRQ1	1000	
	REF5040AQDRQ1	500	
	REF5045AQDRQ1	1000	
	REF5050AQDRQ1	500	
	Machine Model (MM)	200	V
	Charged-Device Model (CDM)	1000	V

## ELECTRICAL CHARACTERISTICS: PER DEVICE

**Boldface** limits apply over the specified temperature range,  $T_A = -40^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ .

$T_A = 25^{\circ}\text{C}$ ,  $I_{\text{LOAD}} = 0$ ,  $C_L = 1\ \mu\text{F}$ ,  $V_{\text{IN}} = (V_{\text{OUT}} + 0.2\ \text{V})$  to  $18\ \text{V}$  (unless otherwise noted).

PARAMETER		CONDITIONS	PER DEVICE			UNIT
			MIN	TYP	MAX	
REF5020 (V <sub>OUT</sub> = 2.048 V) <sup>(1)</sup>						
OUTPUT VOLTAGE		V <sub>OUT</sub>  2.7 V < V <sub>IN</sub> < 18 V	−0.1	2.048	0.1	V
Output voltage						
Initial accuracy:	Standard grade					
NOISE		f = 0.1 Hz to 10 Hz		6		μV <sub>PP</sub>
Output voltage noise						
REF5025 (V <sub>OUT</sub> = 2.5 V)						
OUTPUT VOLTAGE		V <sub>OUT</sub>  Standard grade	−0.1	2.5	0.1	V
Output voltage						
Initial accuracy:	Standard grade					
NOISE		f = 0.1 Hz to 10 Hz		7.5		μV <sub>PP</sub>
Output Voltage Noise						
REF5030 (V <sub>OUT</sub> = 3 V)						
OUTPUT VOLTAGE		V <sub>OUT</sub>  Standard grade	−0.1	3.0	0.1	V
Output voltage						
Initial accuracy:	Standard grade					
NOISE		f = 0.1 Hz to 10 Hz		9		μV <sub>PP</sub>
Output voltage noise						
REF5040 (V <sub>OUT</sub> = 4.096 V)						
OUTPUT VOLTAGE		V <sub>OUT</sub>  Standard grade	−0.05−0.1	4.096	0.05	V
Output voltage						
Initial accuracy:	Standard grade					
NOISE		f = 0.1 Hz to 10 Hz		12		μV <sub>PP</sub>
Output voltage noise						
REF5045 (V <sub>OUT</sub> = 4.5 V)						
OUTPUT VOLTAGE		V <sub>OUT</sub>  Standard grade	−0.1	4.5	0.1	V
Output voltage						
Initial accuracy:	Standard grade					
NOISE		f = 0.1 Hz to 10 Hz		13.5		μV <sub>PP</sub>
Output voltage noise						
REF5050 (V <sub>OUT</sub> = 5 V)						
OUTPUT VOLTAGE		V <sub>OUT</sub>  Standard grade	−0.1	5.0	0.1	V
Output voltage						
Initial accuracy:	Standard grade					
NOISE		f = 0.1 Hz to 10 Hz		15		μV <sub>PP</sub>
Output voltage noise						

(1) For  $V_{\text{OUT}} \leq 2.5\ \text{V}$ , the minimum supply voltage is  $2.7\ \text{V}$ .

## ELECTRICAL CHARACTERISTICS: ALL DEVICES

**Boldface** limits apply over the specified temperature range,  $T_A = -40^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ .

$T_A = 25^{\circ}\text{C}$ ,  $I_{\text{LOAD}} = 0$ ,  $C_L = 1\ \mu\text{F}$ ,  $V_{\text{IN}} = (V_{\text{OUT}} + 0.2\ \text{V})$  to  $18\ \text{V}$  (unless otherwise noted).

PARAMETER		CONDITIONS	REF50xx			UNIT			
			MIN	TYP	MAX				
<b>OUTPUT VOLTAGE TEMPERATURE DRIFT</b>		$V_{IN} = 2.7\text{ V to }18\text{ V}$ $V_{IN} = V_{OUT} + 0.2\text{ V}$		<b>3</b>	<b>8</b>	<b>ppm/°C</b>			
Output voltage temperature drift $dV_{OUT}/dT$									
Standard grade									
<b>LINE REGULATION</b>									
Line regulation $dV_{OUT}/dV_{IN}$									
REF5020 <sup>(1)</sup> only			0.1	1	ppm/V				
All other devices			0.1	1	ppm/V				
Over temperature			<b>0.2</b>	<b>1</b>	<b>ppm/V</b>				
<b>LOAD REGULATION</b>		$-10\text{ mA} < I_{LOAD} < +10\text{ mA}$ $V_{IN} = 3\text{ V}$ $V_{IN} = V_{OUT} + 0.75\text{ V}$							
Load regulation $dV_{OUT}/dI_{LOAD}$									
REF5020 Only							20	30	ppm/mA
All other devices							20	30	ppm/mA
Over temperature								<b>50</b>	<b>ppm/mA</b>
<b>SHORT-CIRCUIT CURRENT</b>		$V_{OUT} = 0\text{ V}$							
Short-circuit current $I_{SC}$									
<b>THERMAL HYSTERESIS</b> <sup>(2)</sup>									
Standard-Grade SO-8		Cycle 1		10		ppm			
Standard-Grade SO-8		Cycle 2		5		ppm			
<b>LONG-TERM STABILITY</b>		0 to 1000 hours 1000 to 2000 hours		90 10		ppm/1000 hr ppm/1000 hr			
SO-8									
SO-8									
<b>TEMP PIN</b>		At $T_A = 25^{\circ}\text{C}$		575 <b>2.64</b>		mV <b>mV/°C</b>			
Voltage output									
Temperature sensitivity									
<b>TURN-ON SETTLING TIME</b>		To 0.1% with $C_L = 1\text{ }\mu\text{F}$		200		$\mu\text{s}$			
Turn-on settling time									
<b>POWER SUPPLY</b>		See Note <sup>(1)</sup>	$V_{OUT} + 0.2^{(1)}$	0.8	18 1 <b>1.2</b>	V mA <b>mA</b>			
Supply voltage $V_S$									
Quiescent current									
Over temperature									
<b>TEMPERATURE RANGE</b>				150					
Specified range									
Operating range									
Thermal resistance $\theta_{JA}$									
SO-8									

(1) For  $V_{\text{OUT}} \leq 2.5\ \text{V}$ , the minimal supply voltage is  $2.7\ \text{V}$ .

(2) The thermal hysteresis procedure is explained in more detail in the [Application Information](#) section.

## TYPICAL CHARACTERISTICS

$T_A = 25^\circ\text{C}$ ,  $I_{\text{LOAD}} = 0$ ,  $V_S = V_{\text{OUT}} + 0.2\text{ V}$  (unless otherwise noted). For  $V_{\text{OUT}} \leq 2.5\text{ V}$ , the minimum supply voltage is 2.7 V.

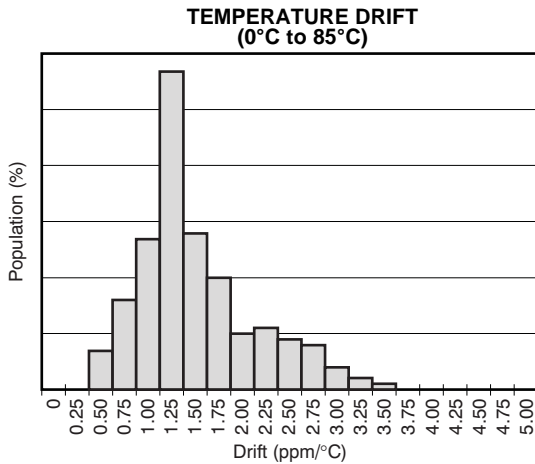


Figure 1.

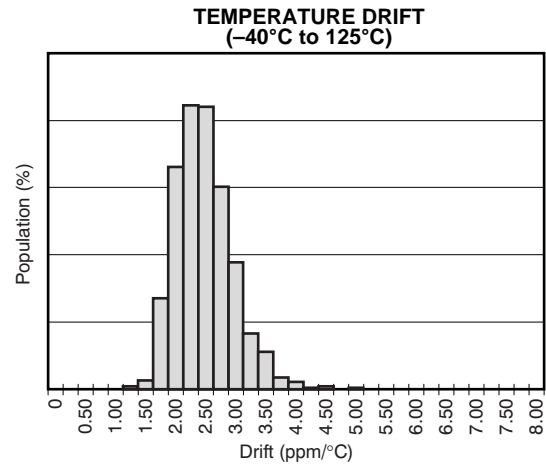


Figure 2.

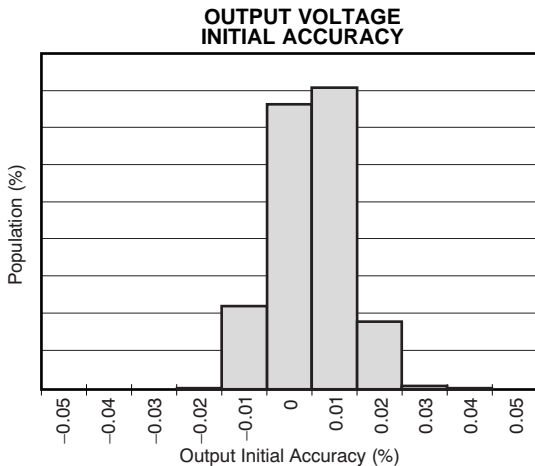


Figure 3.

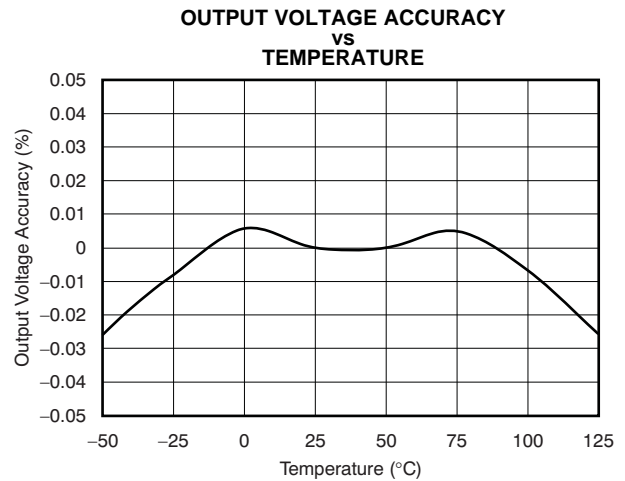


Figure 4.

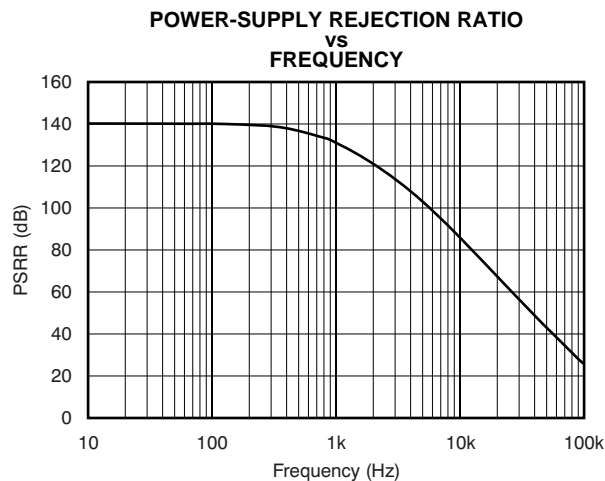


Figure 5.

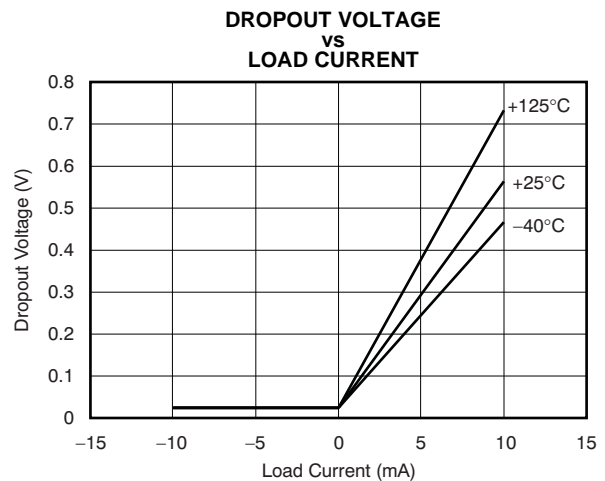
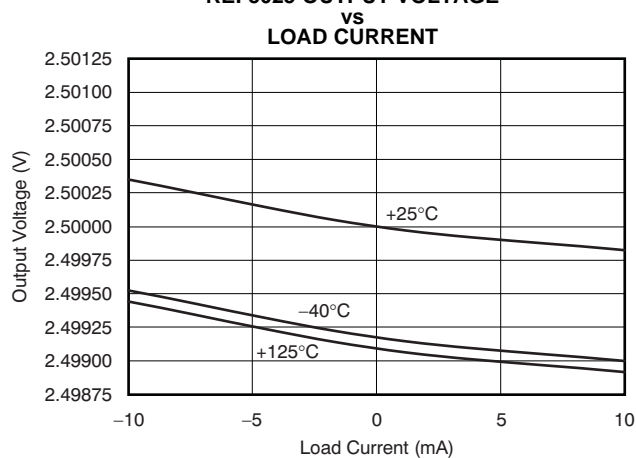


Figure 6.

## TYPICAL CHARACTERISTICS (continued)

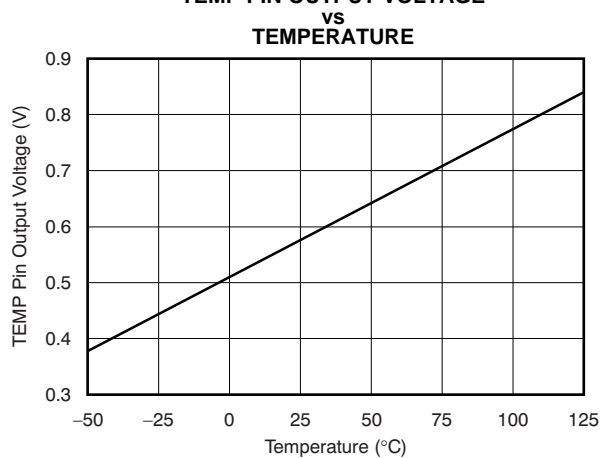
$T_A = 25^\circ\text{C}$ ,  $I_{\text{LOAD}} = 0$ ,  $V_S = V_{\text{OUT}} + 0.2\text{ V}$  (unless otherwise noted). For  $V_{\text{OUT}} \leq 2.5\text{ V}$ , the minimum supply voltage is 2.7 V.

**REF5025 OUTPUT VOLTAGE**



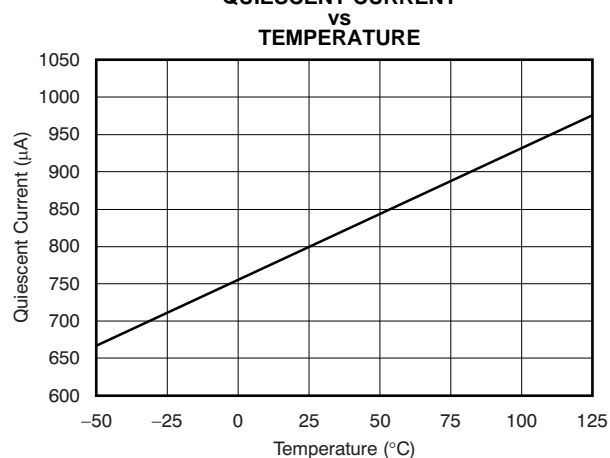
**Figure 7.**

**TEMP PIN OUTPUT VOLTAGE**



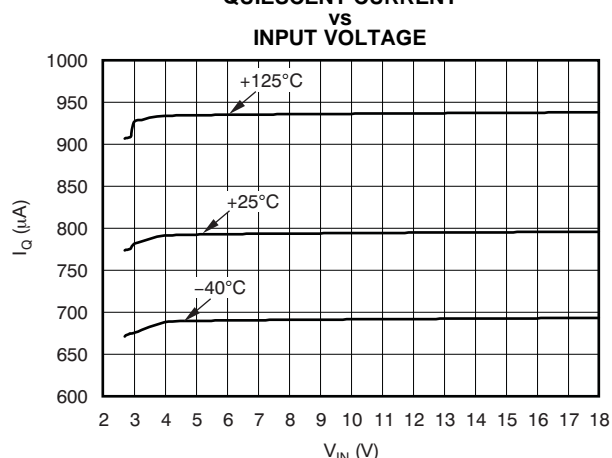
**Figure 8.**

**QUIESCENT CURRENT**



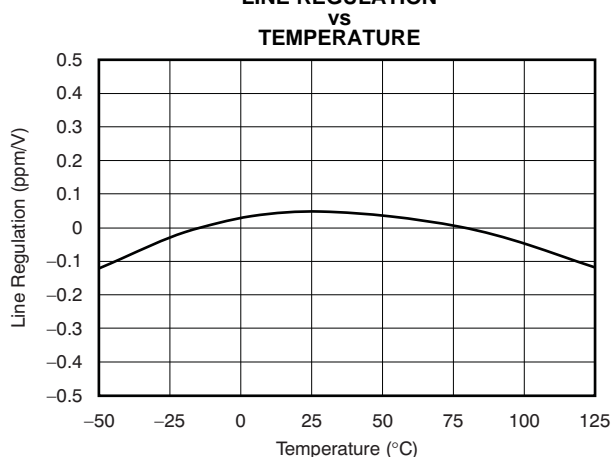
**Figure 9.**

**QUIESCENT CURRENT**



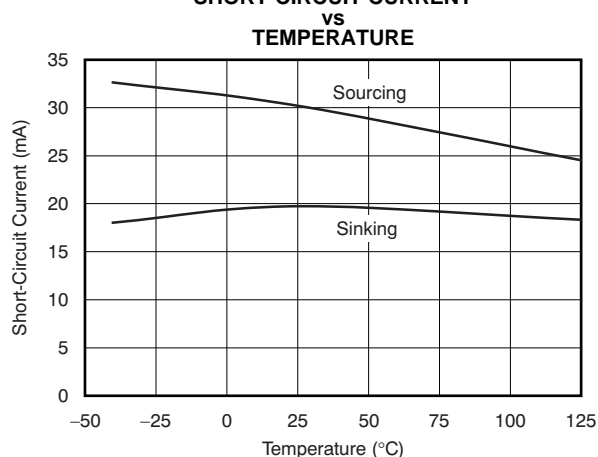
**Figure 10.**

**LINE REGULATION**



**Figure 11.**

**SHORT-CIRCUIT CURRENT**



**Figure 12.**

## TYPICAL CHARACTERISTICS (continued)

$T_A = 25^\circ\text{C}$ ,  $I_{\text{LOAD}} = 0$ ,  $V_S = V_{\text{OUT}} + 0.2\text{ V}$  (unless otherwise noted). For  $V_{\text{OUT}} \leq 2.5\text{ V}$ , the minimum supply voltage is 2.7 V.

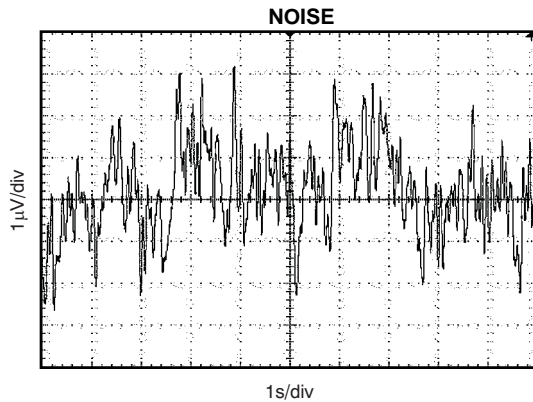


Figure 13.

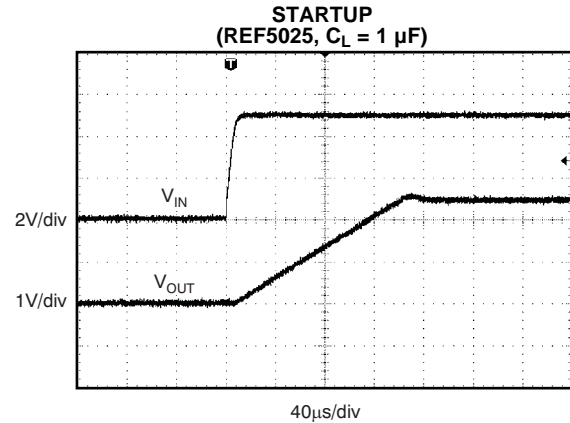


Figure 14.

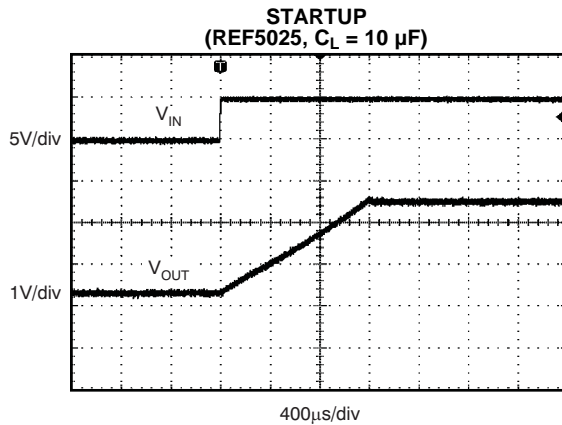


Figure 15.

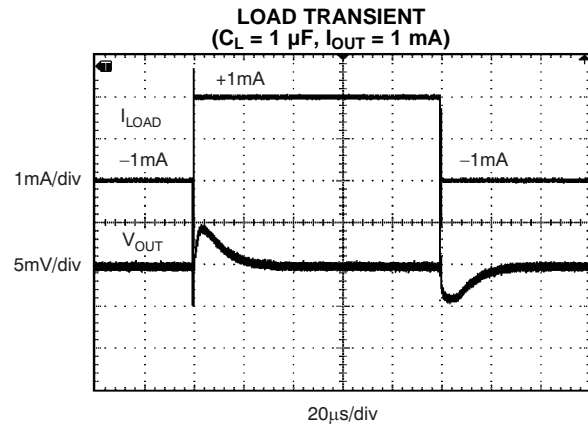


Figure 16.

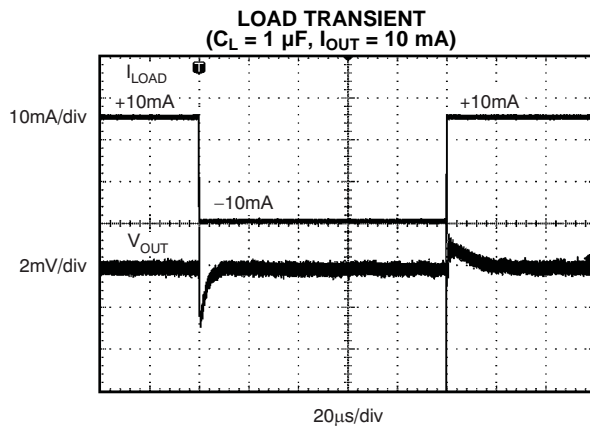


Figure 17.

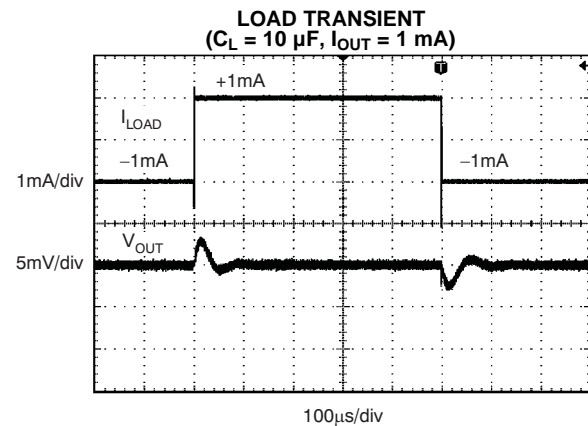


Figure 18.

## TYPICAL CHARACTERISTICS (continued)

$T_A = 25^\circ\text{C}$ ,  $I_{\text{LOAD}} = 0$ ,  $V_S = V_{\text{OUT}} + 0.2\text{ V}$  (unless otherwise noted). For  $V_{\text{OUT}} \leq 2.5\text{ V}$ , the minimum supply voltage is 2.7 V.

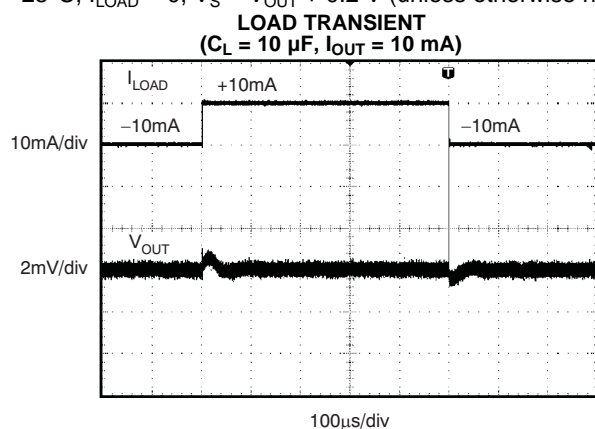


Figure 19.

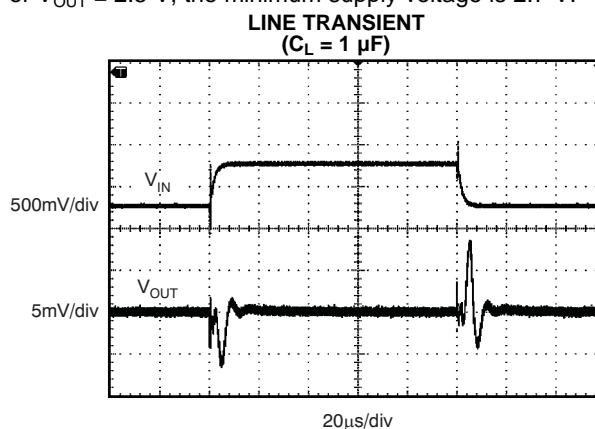


Figure 20.

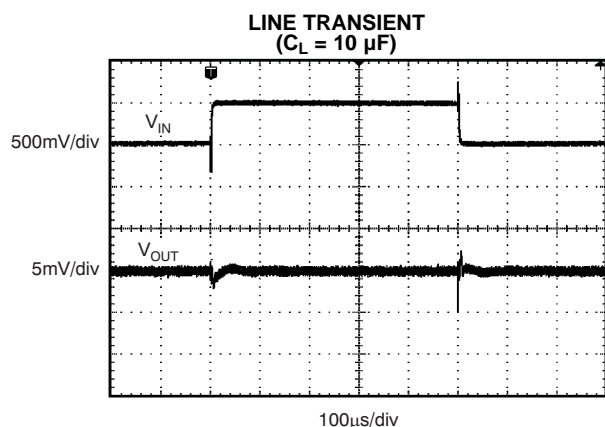


Figure 21.

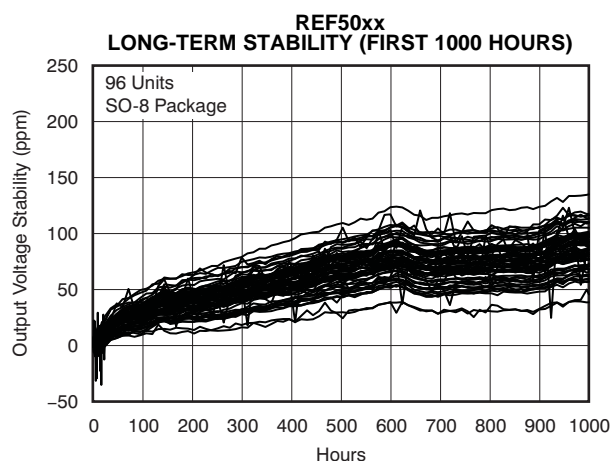


Figure 22.

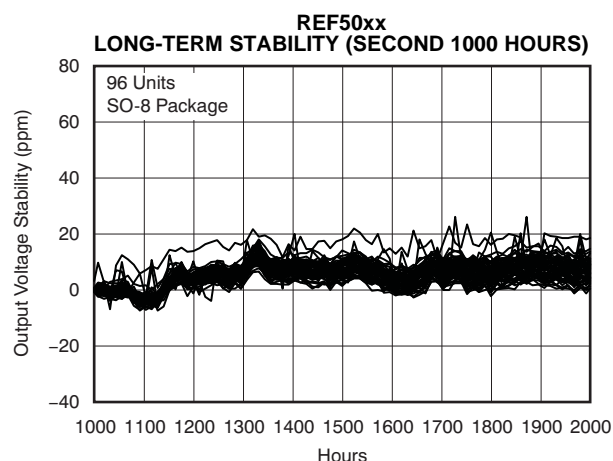


Figure 23.

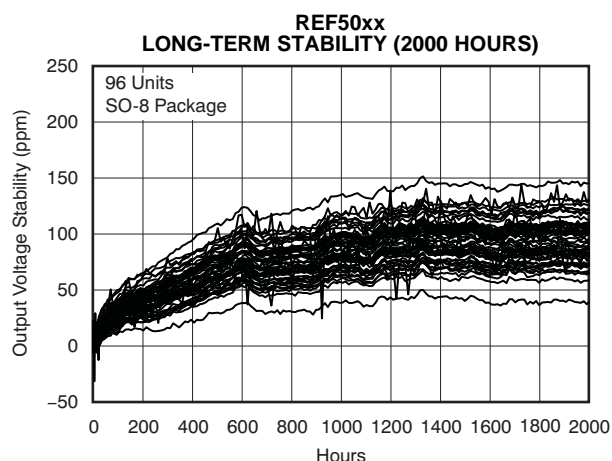


Figure 24.

## APPLICATION INFORMATION

The REF50xx is family of low-noise, precision-bandgap voltage references that are specifically designed for excellent initial voltage accuracy and drift. Figure 25 shows a simplified block diagram of the REF50xx.

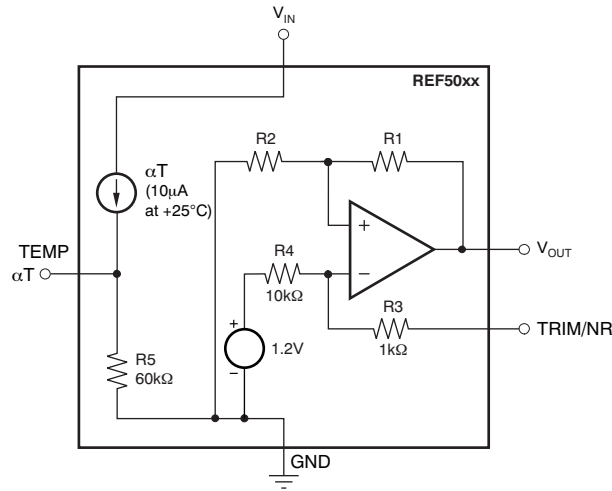


Figure 25. REF50xx Simplified Block Diagram

## BASIC CONNECTIONS

Figure 26 shows the typical connections for the REF50xx. A supply bypass capacitor ranging between 1 µF to 10 µF is recommended. A 1-µF to 50-µF, low-ESR output capacitor ( $C_L$ ) must be connected from  $V_{OUT}$  to GND. The ESR value should be less than or equal to 1.5 Ω. The ESR minimizes gain peaking of the internal 1.2-V reference and thus reduces noise at the  $V_{OUT}$  pin.

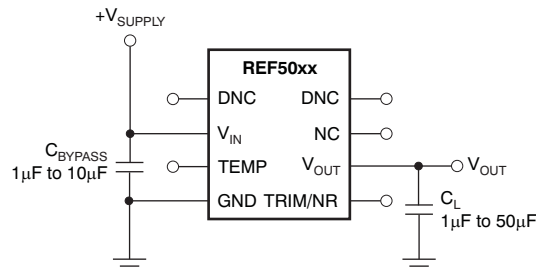


Figure 26. Basic Connections

## SUPPLY VOLTAGE

The REF50xx family of voltage references features extremely low dropout voltage. With the exception of the REF5020, which has a minimum supply requirement of 2.7 V, these references can be operated with a supply of 200 mV above the output voltage in an unloaded condition. For loaded conditions, a typical dropout voltage versus load plot is shown in Figure 6 of the *Typical Characteristics*.

## USING THE TRIM/NR PIN

The REF50xx provides a very accurate voltage output. However,  $V_{OUT}$  can be adjusted to reduce noise and shift the output voltage from the nominal value by configuring the trim and noise reduction pin (TRIM/NR, pin 5). The TRIM/NR pin provides a  $\pm 15$ -mV adjustment of the device bandgap, which produces a  $\pm 15$ -mV change on the  $V_{OUT}$  pin. Figure 27 shows a typical circuit using the TRIM/NR pin to adjust  $V_{OUT}$ . When using this technique, the temperature coefficients of the resistors can degrade the temperature drift at the output.

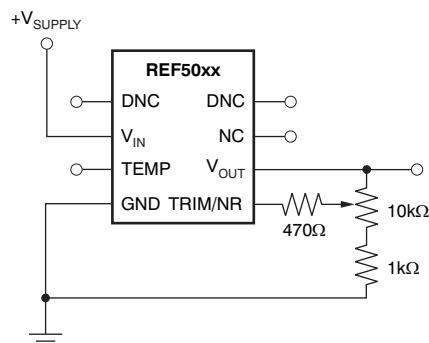


Figure 27.  $V_{OUT}$  Adjustment Using TRIM/NR Pin

The REF50xx allows access to the bandgap through the TRIM/NR pin. Placing a capacitor from the TRIM/NR pin to GND (as Figure 28 illustrates) in combination with the internal 1-kΩ resistor creates a low-pass filter that lowers the overall noise measured on the  $V_{OUT}$  pin. A capacitance of 1  $\mu$ F is suggested for a low-pass filter with a corner frequency of 14.5 Hz. Higher capacitance results in a lower cutoff frequency.

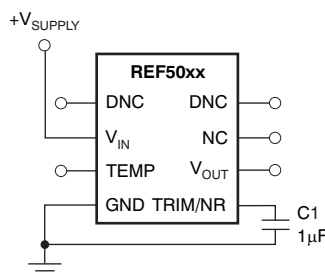


Figure 28. Noise Reduction Using TRIM/NR Pin

## TEMPERATURE DRIFT

The REF50xx is designed for minimal drift error, which is defined as the change in output voltage over temperature. The drift is calculated using the box method, as described by the following equation:

$$\text{Drift} = \left( \frac{V_{OUTMAX} - V_{OUTMIN}}{V_{OUT} \times \text{Temp Range}} \right) \times 10^6 (\text{ppm}) \quad (1)$$

The REF50xx features a maximum drift coefficient of 8 ppm/°C for the standard-grade.

## THERMAL HYSTERESIS

Thermal hysteresis for the REF50xx is defined as the change in output voltage after operating the device at +25°C, cycling the device through the specified temperature range, and returning to +25°C. It can be expressed as Equation 2:

$$V_{\text{HYST}} = \left( \frac{|V_{\text{PRE}} - V_{\text{POST}}|}{V_{\text{NOM}}} \right) \cdot 10^6 (\text{ppm})$$

where

- $V_{\text{HYST}}$  = thermal hysteresis (in units of ppm)
  - $V_{\text{NOM}}$  = the specified output voltage
  - $V_{\text{PRE}}$  = output voltage measured at +25°C pretemperature cycling
  - $V_{\text{POST}}$  = output voltage measured after the device has been cycled from +25°C through the specified temperature range of –40°C to +125°C and returned to +25°C
- (2)

## TEMPERATURE MONITORING

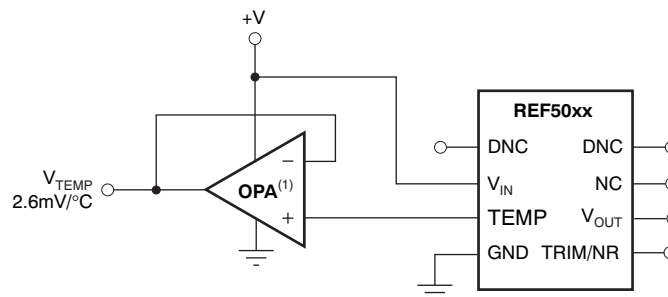
The temperature output terminal (TEMP, pin 3) provides a temperature-dependent voltage output with approximately 60-kΩ source impedance. As seen in Figure 8, the output voltage follows the nominal relationship:

$$V_{\text{TEMP PIN}} = 509 \text{ mV} + 2.64 \times T(^{\circ}\text{C}) \quad (3)$$

This pin indicates general chip temperature, accurate to approximately ±15°C. Although it is not generally suitable for accurate temperature measurements, it can be used to indicate temperature changes or for temperature compensation of analog circuitry. A temperature change of 30°C corresponds to an approximate 79-mV change in voltage at the TEMP pin.

The TEMP pin has high output impedance (see Figure 25). Loading this pin with a low-impedance circuit induces a measurement error; however, it does not have any effect on  $V_{\text{OUT}}$  accuracy.

To avoid errors caused by low-impedance loading, buffer the TEMP pin output with a suitable low-temperature drift op amp, such as the OPA333, OPA335, or OPA376, as shown in Figure 29.



NOTE: (1) Low drift op amp, such as the OPA333, OPA335, or OPA376.

Figure 29. Buffering the TEMP Pin Output

## POWER DISSIPATION

The REF50xx family is specified to deliver current loads of ±10 mA over the specified input voltage range. The temperature of the device increases according to the equation:

$$T_J = T_A + P_D \times \theta_{JA}$$

where

- $T_J$  = Junction temperature (°C)
  - $T_A$  = Ambient temperature (°C)
  - $P_D$  = Power dissipated (W)
  - $\theta_{JA}$  = Junction-to-ambient thermal resistance (°C/W)
- (4)

The REF50xx junction temperature must not exceed the absolute maximum rating of 150°C.

## NOISE PERFORMANCE

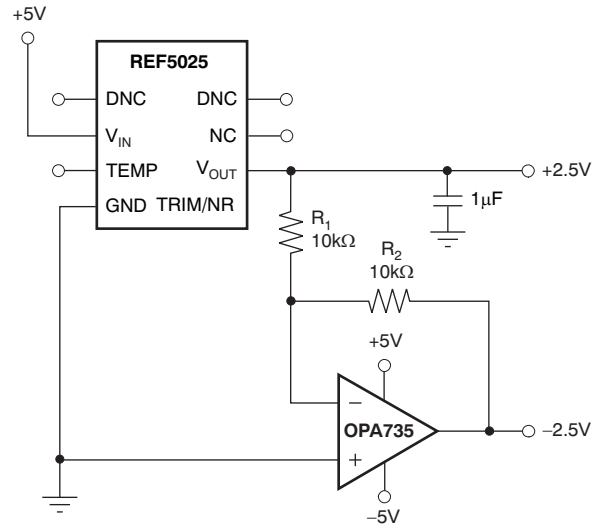
Typical 0.1Hz to 10Hz voltage noise for each member of the REF50xx family is specified in the [Electrical Characteristics: Per Device](#) table. The noise voltage increases with output voltage and operating temperature. Additional filtering can be used to improve output noise levels, although care should be taken to ensure the output impedance does not degrade performance.

For additional information about how to minimize noise and maximize performance in mixed-signal applications such as data converters, refer to the series of *Analog Applications Journal* articles entitled, *How a Voltage Reference Affects ADC Performance*. This three-part series is available for download from the TI website under three literature numbers: [SLYT331](#), [SLYT339](#), and [SLYT355](#) for [Part I](#), [Part II](#), and [Part III](#), respectively.

## APPLICATION CIRCUITS

### NEGATIVE REFERENCE VOLTAGE

For applications requiring a negative and positive reference voltage, the REF50xx and OPA735 can be used to provide a dual-supply reference from a 5-V supply. Figure 30 shows the REF5025 used to provide a 2.5-V supply reference voltage. The low drift performance of the REF50xx complements the low offset voltage and zero drift of the OPA735 to provide an accurate solution for split-supply applications. Care must be taken to match the temperature coefficients of  $R_1$  and  $R_2$ .



NOTE: Bypass capacitors not shown.

Figure 30. The REF5025 and OPA735 Create Positive and Negative Reference Voltages

### DATA ACQUISITION

Data acquisition systems often require stable voltage references to maintain accuracy. The REF50xx family features low noise, very low drift, and high initial accuracy for high-performance data converters. Figure 31 shows the REF5040 in a basic data acquisition system.

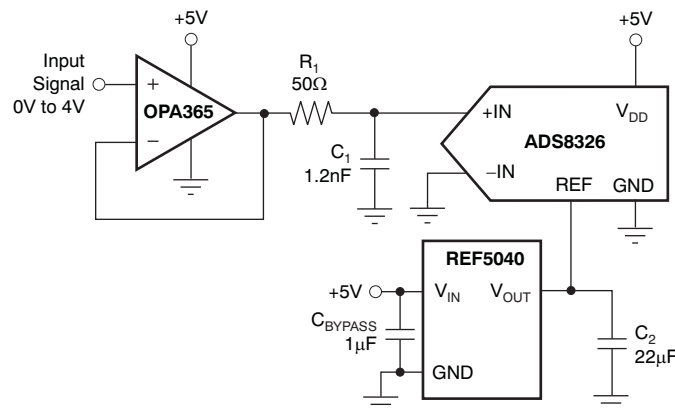


Figure 31. Basic Data Acquisition System

## REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision F (September 2011) to Revision G	Page
• Deleted reference to <i>high grade</i> throughout the document .....	1
• Deleted <i>Package/Ordering Information</i> table from datasheet .....	2
• Deleted references to the MSOP-8 package and <i>High-Grade</i> from the <i>THERMAL HYSTERESIS</i> section of the <i>ELECTRICAL CHARACTERISTICS: ALL DEVICES</i> table .....	4
• Deleted references to the MSOP-8 package from the <i>LONG-TERM STABILITY</i> section of the <i>ELECTRICAL CHARACTERISTICS: ALL DEVICES</i> table .....	4
• Deleted graphs for MSOP-8 package from <i>TYPICAL CHARACTERISTICS</i> section .....	8
Changes from Revision E (August 2011) to Revision F	Page
• Added REF5045AQDRQ1 HBM ESD rating of 1000 V .....	2
Changes from Revision D (October, 2010) to Revision E	Page
• Added <i>Thermal Hysteresis</i> parameters and specifications .....	4
• Added <i>Long-Term Stability</i> parameters and specifications .....	4
• Added <a href="#">Figure 22</a> through <a href="#">Figure 24</a> .....	8
• Added <a href="#">Thermal Hysteresis</a> section .....	11
• Revised <a href="#">Noise Performance</a> section; added paragraph with links to applications articles .....	12

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
REF5020AQDRQ1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	RFQ 5020 A	<a href="#">Samples</a>
REF5025AQDRQ1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	RFQ 5025 A	<a href="#">Samples</a>
REF5030AQDRQ1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	RFQ 5030 A	<a href="#">Samples</a>
REF5040AQDRQ1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	RFQ 5040 A	<a href="#">Samples</a>
REF5045AQDRQ1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	RFQ 5045 A	<a href="#">Samples</a>
REF5050AQDRQ1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	RFQ 5050 A	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

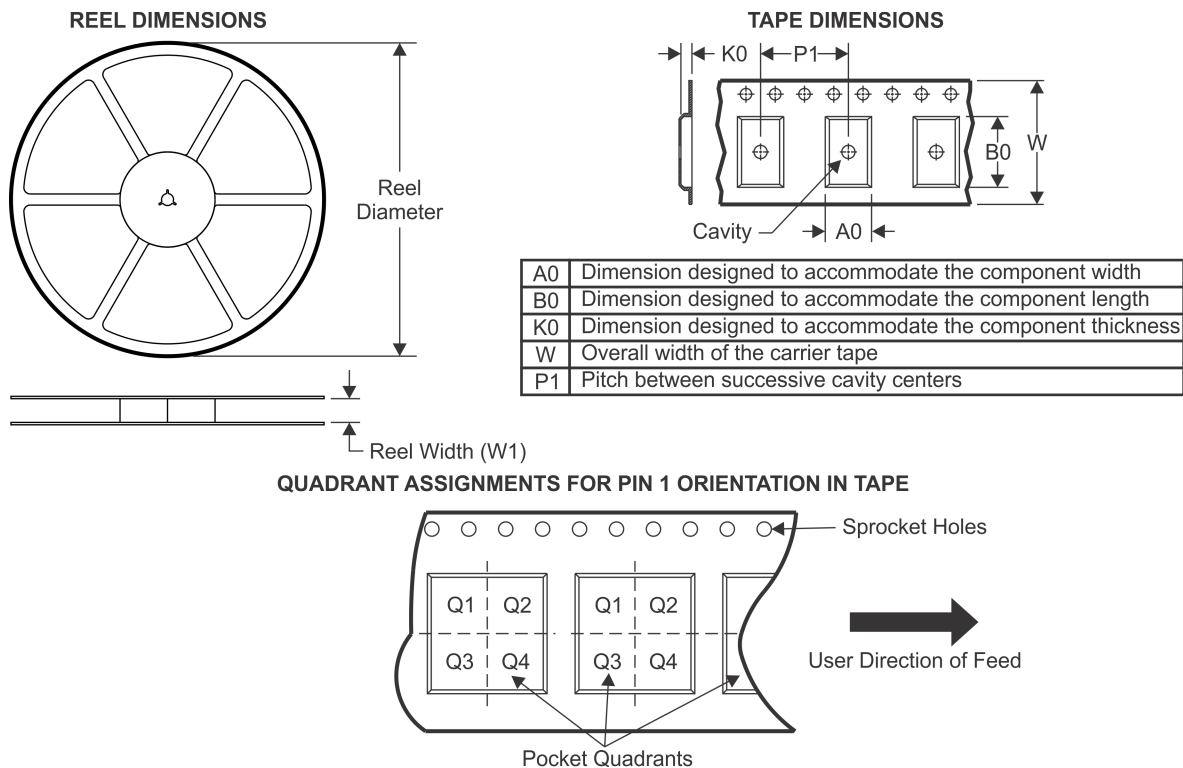
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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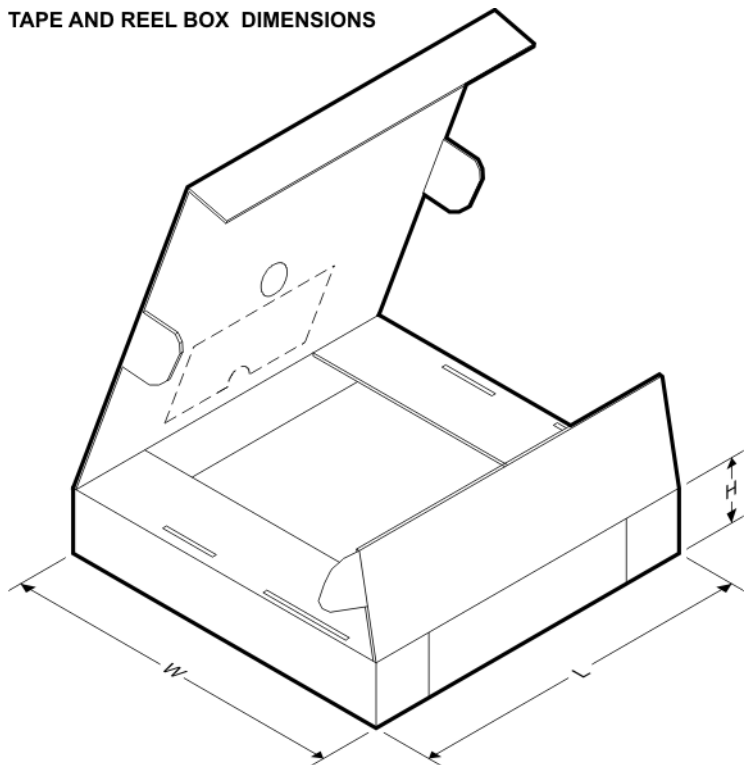
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**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
REF5020AQDRQ1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
REF5025AQDRQ1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
REF5030AQDRQ1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
REF5040AQDRQ1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
REF5045AQDRQ1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
REF5050AQDRQ1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

## TAPE AND REEL BOX DIMENSIONS

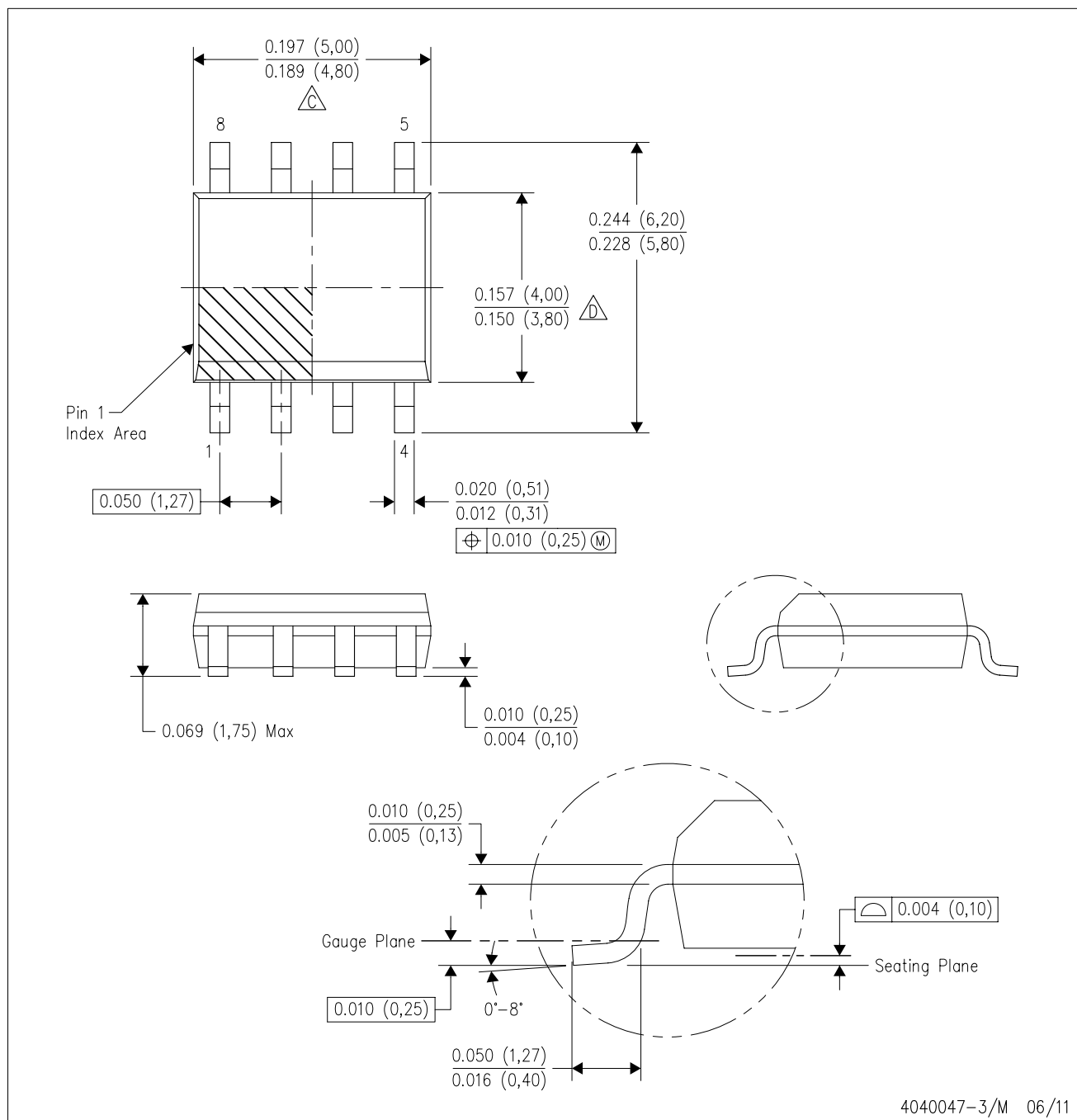


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
REF5020AQDRQ1	SOIC	D	8	2500	367.0	367.0	35.0
REF5025AQDRQ1	SOIC	D	8	2500	367.0	367.0	35.0
REF5030AQDRQ1	SOIC	D	8	2500	367.0	367.0	35.0
REF5040AQDRQ1	SOIC	D	8	2500	367.0	367.0	35.0
REF5045AQDRQ1	SOIC	D	8	2500	367.0	367.0	35.0
REF5050AQDRQ1	SOIC	D	8	2500	367.0	367.0	35.0

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE

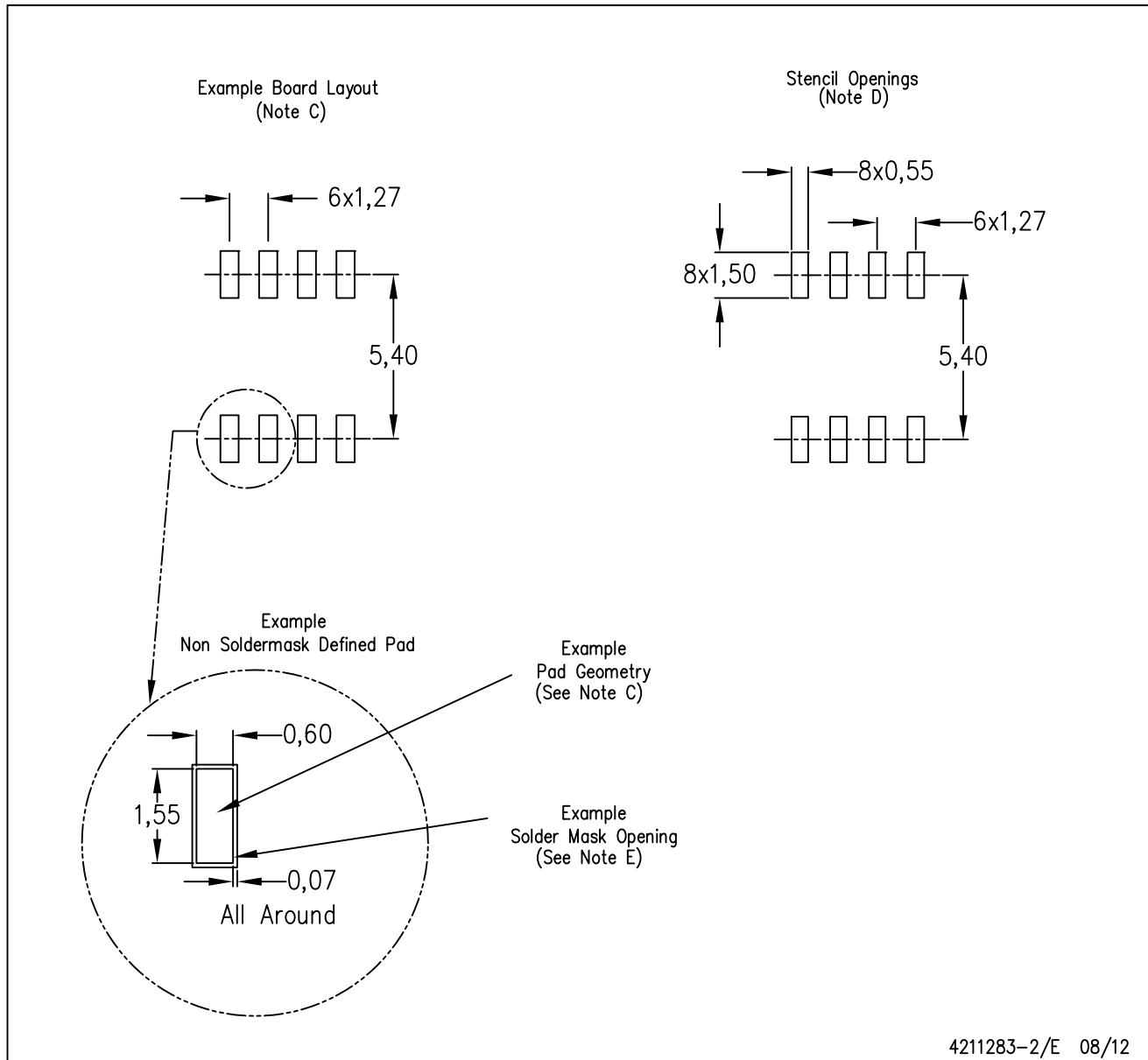


## NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- $\triangle C$  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- $\triangle D$  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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